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Transmitted herewith for filing is the Patent Application of:

Inventor: JIN YUAN LEE, CHING CHENG HUANG, MOU SHIANG LIN

For: A STRUCTURE AND MANUFACTURING METHOD OF CHIP SCALE PACKAGE

Enclosed are:

- ☒ 10 sheets of drawing(s) - formal.
- ☒ An assignment of the invention to **MEGIC CORPORATION**
- ☐ An associate power of attorney ☒ Applicant claims small entity status
- ☐ Request & Certification under 35 USC 122(b) (2) (b) (i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)		SMALL ENTITY
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 345.
TOTAL CLAIMS	41 -20=	21	x 9 =	\$ 189.
INDEP CLAIMS	3 -3=	0	x 40 =	\$ 0.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
SUB TOTAL				\$ 534.
ASSIGNMENT				\$40.
TOTAL				\$574.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of \$ 574. A duplicate copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
 - ☒ Any additional filing fees required under 37 CFR \$1.16.
 - ☒ Any patent application processing fees under 37 CFR \$1.17.

Respectfully submitted,

STEPHEN B. ACKERMAN, REG. NO. 37,761